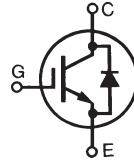


**1200V XPT™ IGBT
GenX3™ w/ Diode**
IXYR50N120C3D1
(Electrically Isolated Tab)

 High-Speed IGBT
for 20-50 kHz Switching


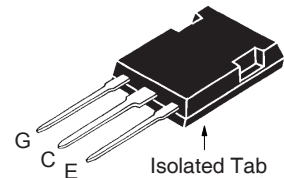
$$V_{CES} = 1200V$$

$$I_{C90} = 32A$$

$$V_{CE(sat)} \leq 4.0V$$

$$t_{fi(typ)} = 43ns$$

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_J = 25^\circ C$ to $150^\circ C$	1200	V
V_{CGR}	$T_J = 25^\circ C$ to $150^\circ C$, $R_{GE} = 1M\Omega$	1200	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ C$ (Chip Capability)	56	A
I_{C90}	$T_C = 90^\circ C$	32	A
I_{F110}	$T_C = 110^\circ C$	18	A
I_{CM}	$T_C = 25^\circ C$, 1ms	210	A
SSOA	$V_{GE} = 15V$, $T_{VJ} = 150^\circ C$, $R_G = 5\Omega$	$I_{CM} = 100$	A
(RBSOA)	Clamped Inductive Load	@ $V_{CE} \leq V_{CES}$	
P_C	$T_C = 25^\circ C$	290	W
T_J		-55 ... +150	$^\circ C$
T_{JM}		150	$^\circ C$
T_{stg}		-55 ... +150	$^\circ C$
T_L	Maximum Lead Temperature for Soldering	300	$^\circ C$
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	$^\circ C$
V_{ISOL}	50/60 Hz, 1 Minute	2500	V~
F_C	Mounting Force	20..120/4.5..27	N/lb.
Weight		5	g

ISOPLUS247™

 G = Gate C = Collector
E = Emitter

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 2500V~ Electrical Isolation
- Optimized for Low Switching Losses
- Square RBSOA
- Positive Thermal Coefficient of $V_{ce(sat)}$
- Anti-Parallel Ultra Fast Diode
- High Current Handling Capability
- International Standard Package

Advantages

- High Power Density
- Low Gate Drive Requirement

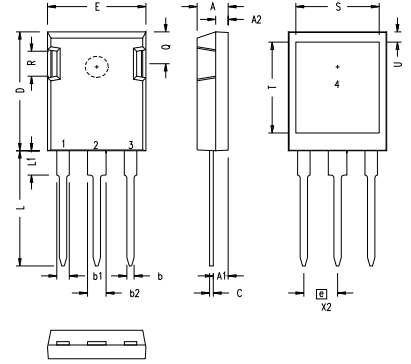
Applications

- High Frequency Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	$I_C = 250\mu A$, $V_{GE} = 0V$	1200		V
$V_{GE(th)}$	$I_C = 250\mu A$, $V_{CE} = V_{GE}$	3.0		5.0 V
I_{CES}	$V_{CE} = V_{CES}$, $V_{GE} = 0V$ $T_J = 125^\circ C$			50 μA 500 μA
I_{GES}	$V_{CE} = 0V$, $V_{GE} = \pm 20V$			± 100 nA
$V_{CE(sat)}$	$I_C = 50A$, $V_{GE} = 15V$, Note 1 $T_J = 150^\circ C$	4.2		4.0 V V

Symbol Test Conditions		Characteristic Values		
(T _J = 25°C Unless Otherwise Specified)		Min.	Typ.	Max.
g_{fs}	I _C = 50A, V _{CE} = 10V, Note 1	20	32	S
C_{ies}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz		3100	pF
C_{oes}			230	pF
C_{res}			66	pF
Q_{g(on)}	I _C = 50A, V _{GE} = 15V, V _{CE} = 0.5 • V _{CES}		142	nC
Q_{ge}			23	nC
Q_{gc}			60	nC
t_{d(on)}	Inductive load, T _J = 25°C I _C = 50A, V _{GE} = 15V V _{CE} = 0.5 • V _{CES} , R _G = 5Ω Note 2		28	ns
t_{ri}			62	ns
E_{on}			3.0	mJ
t_{d(off)}			133	ns
t_{fi}			43	ns
E_{off}			1.0	1.7 mJ
t_{d(on)}	Inductive load, T _J = 150°C I _C = 50A, V _{GE} = 15V V _{CE} = 0.5 • V _{CES} , R _G = 5Ω Note 2		28	ns
t_{ri}			68	ns
E_{on}			6.0	mJ
t_{d(off)}			160	ns
t_{fi}			60	ns
E_{off}			1.4	mJ
R_{thJC}				0.43 °C/W
R_{thCS}		0.15		°C/W

ISOPLUS247 (IXYR) Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b1	.075	.084	1.91	2.13
b2	.115	.123	2.92	3.12
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
E	.620	.635	15.75	16.13
e	.215 BSC		5.45 BSC	
L	.780	.800	19.81	20.32
L1	.150	.170	3.81	4.32
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.520	.540	13.21	13.72
T	.620	.640	15.75	16.26
U	.065	.080	1.65	2.03

- 1 - Gate
- 2,4 - Collector
- 3 - Emitter

Reverse Diode (FRED)

Symbol Test Conditions		Characteristic Value		
(T _J = 25°C, Unless Otherwise Specified)		Min.	Typ.	Max.
V_F	I _F = 30A, V _{GE} = 0V, Note 1 T _J = 150°C		1.75	3.00 V V
I_{RM}	I _F = 30A, V _{GE} = 0V, -di _F /dt = 100A/μs, T _J = 100°C V _R = 600V T _J = 100°C			9 A
t_{rr}			195	ns
R_{thJC}				1.10 °C/W

Notes:

- Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
- Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

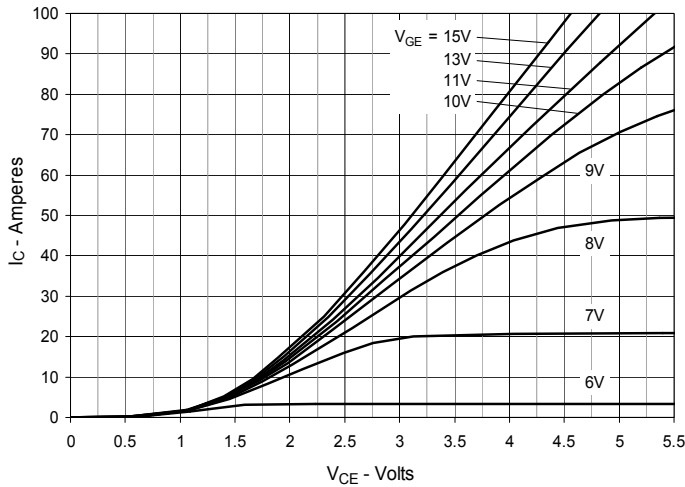
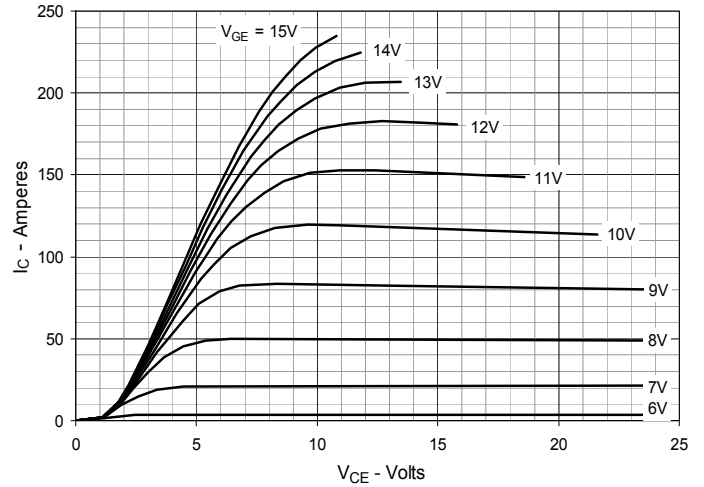
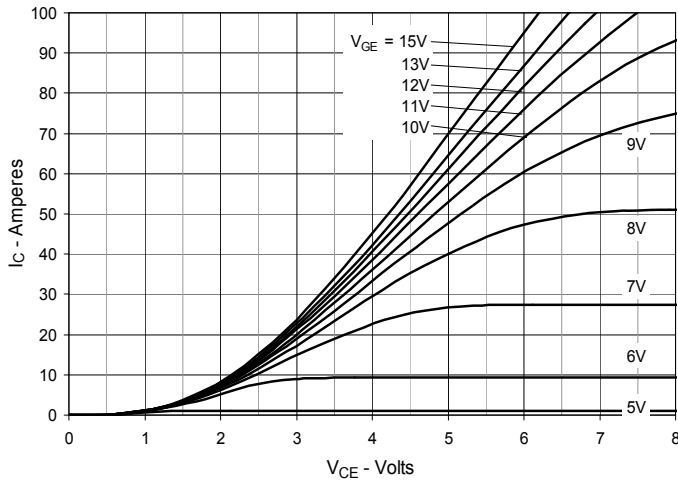
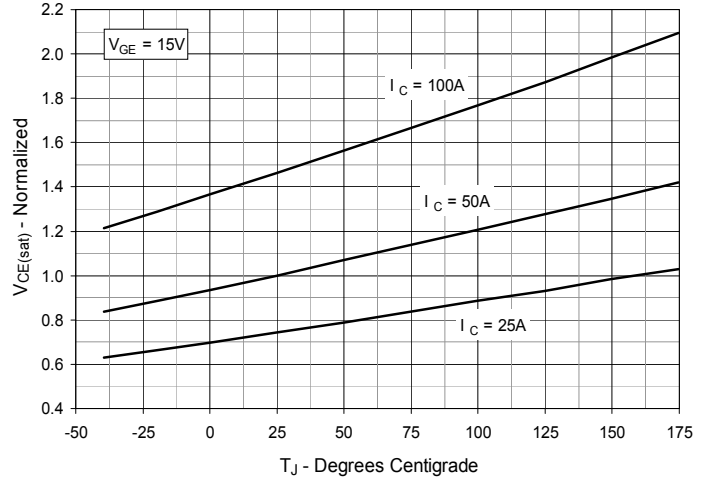
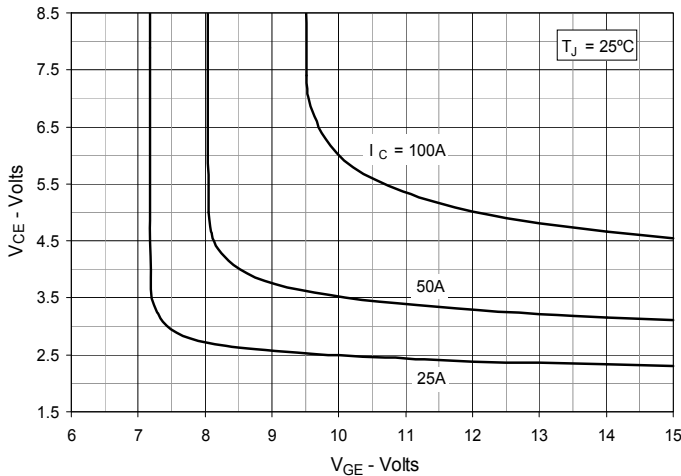
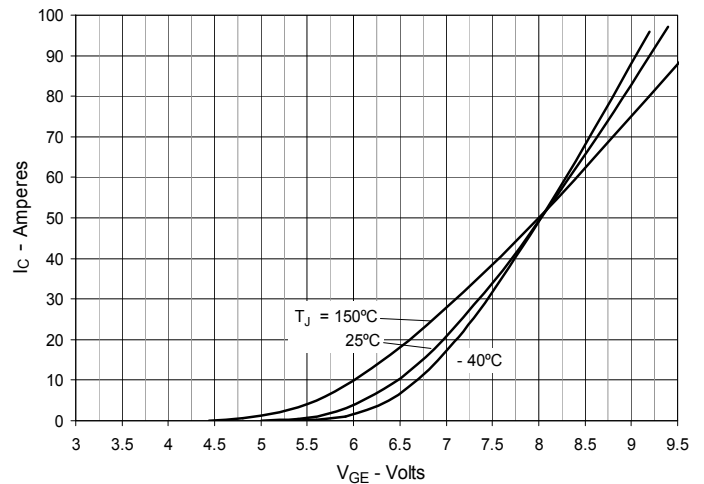
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$

Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

Fig. 6. Input Admittance


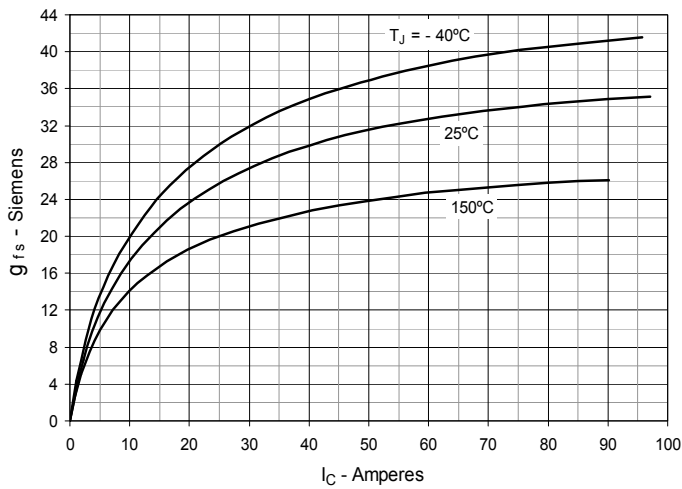
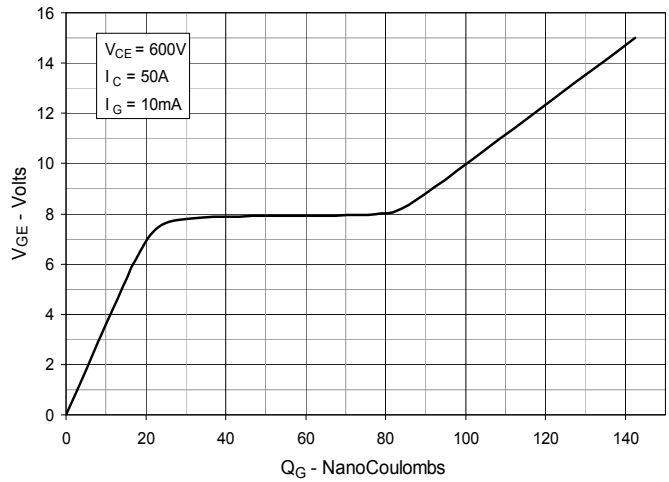
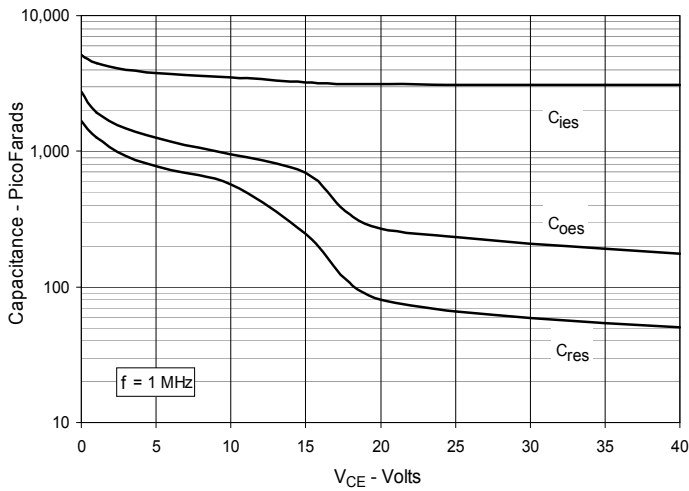
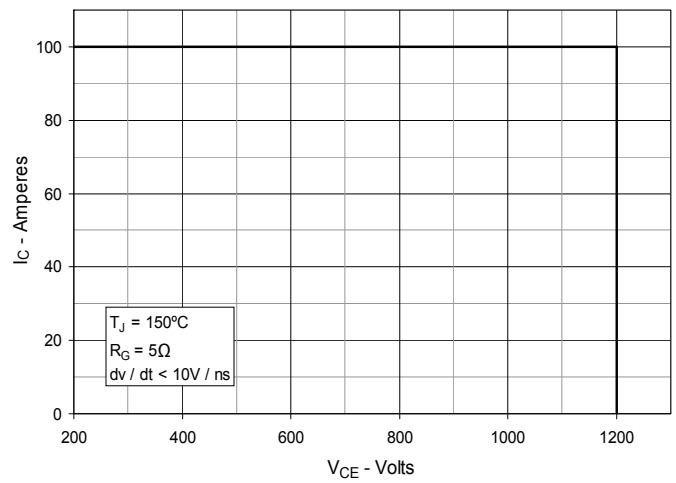
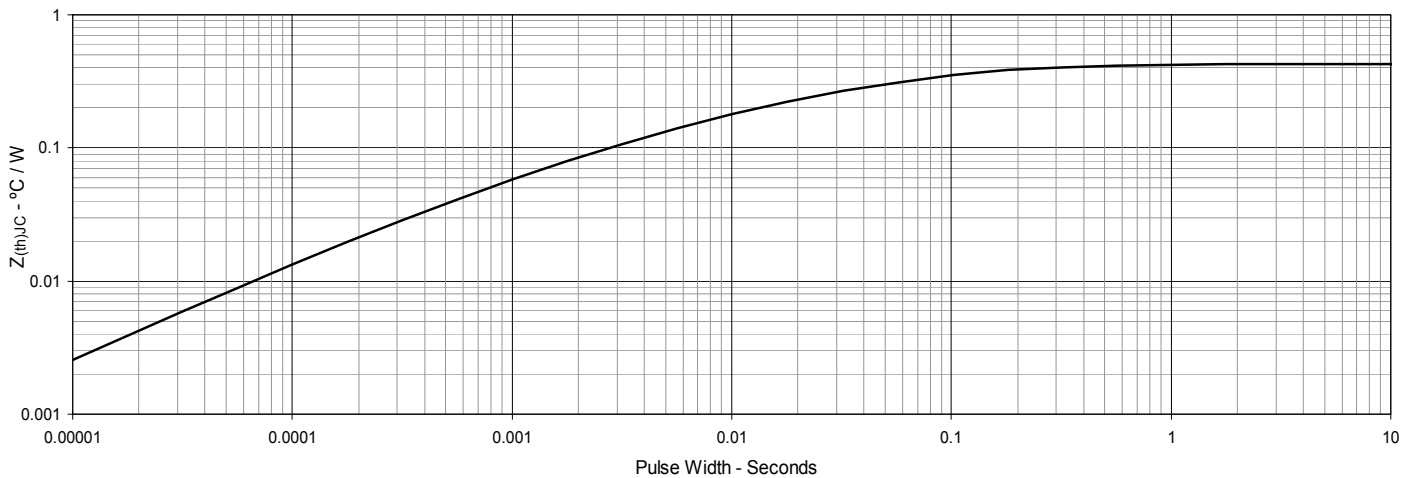
Fig. 7. Transconductance

Fig. 8. Gate Charge

Fig. 9. Capacitance

Fig. 10. Reverse-Bias Safe Operating Area

Fig. 11. Maximum Transient Thermal Impedance


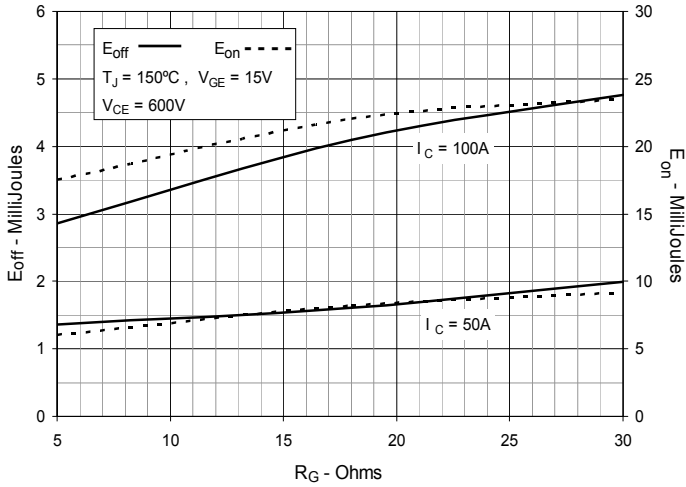
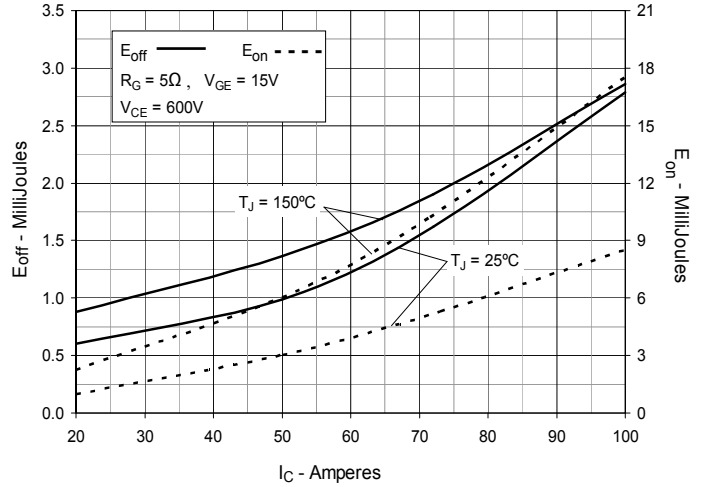
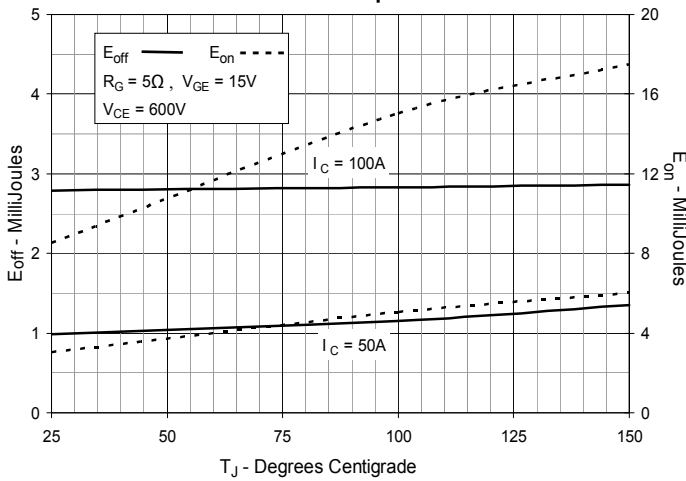
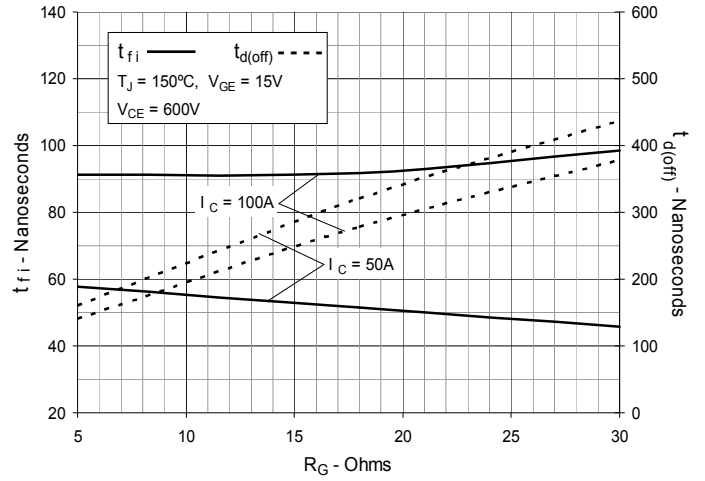
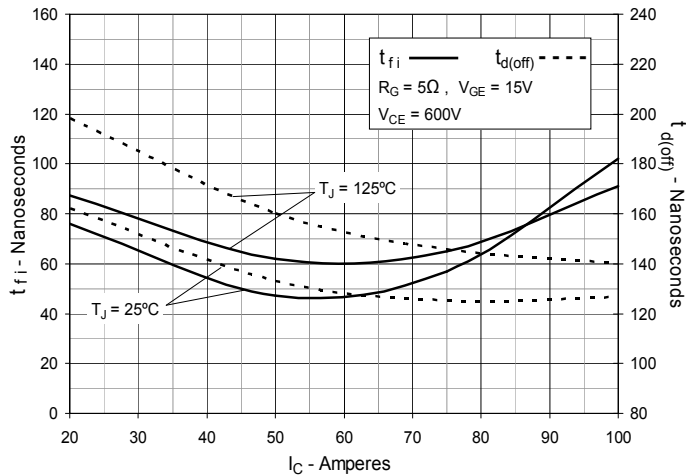
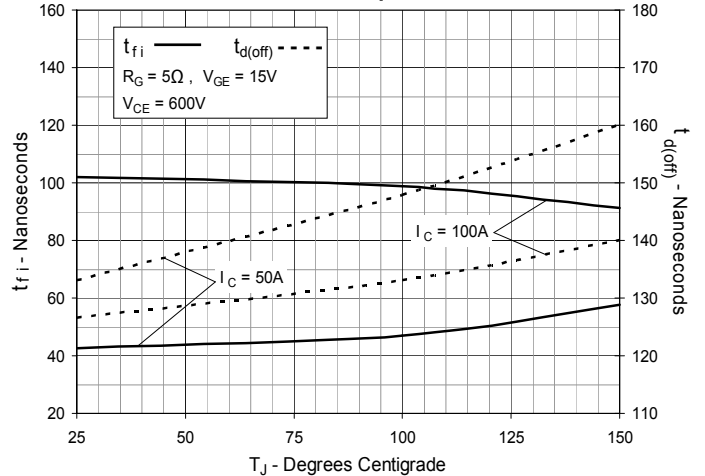
Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

Fig. 13. Inductive Switching Energy Loss vs. Collector Current

Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

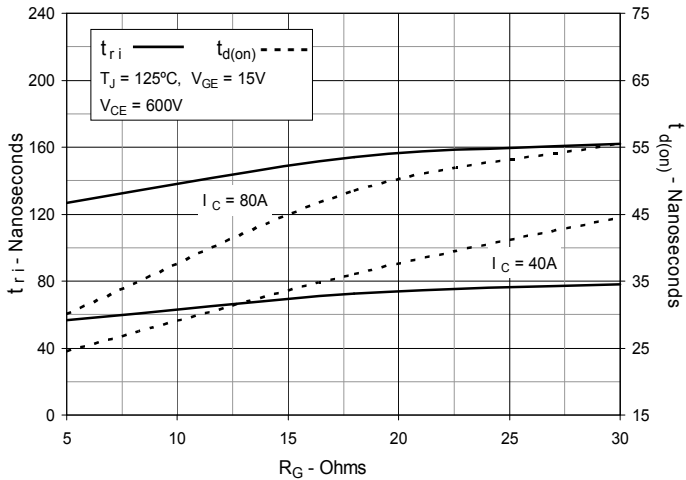


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

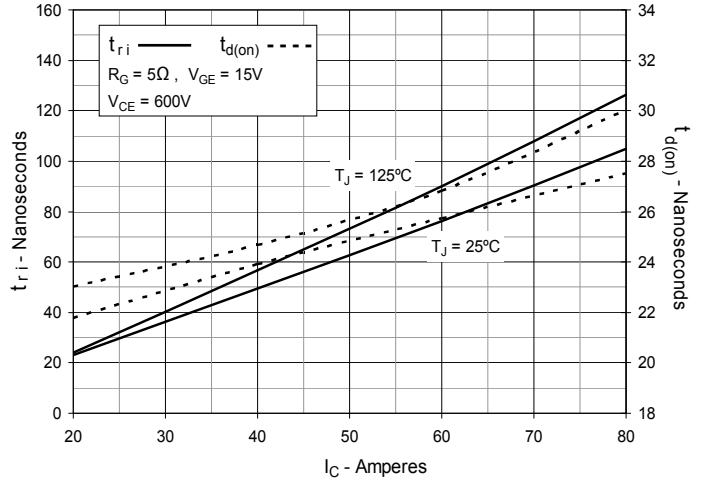


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature

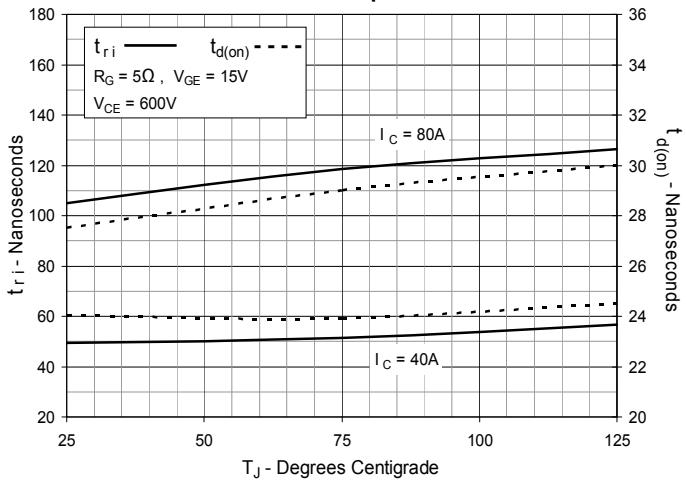


Fig. 21. Maximum Transient Thermal Impedance (Diode)

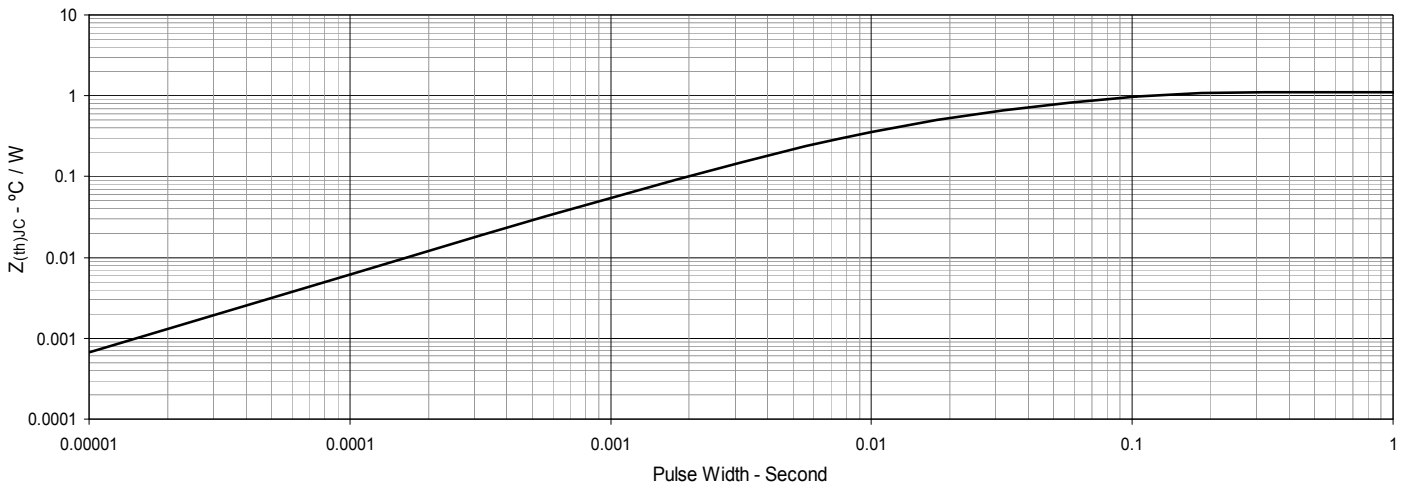
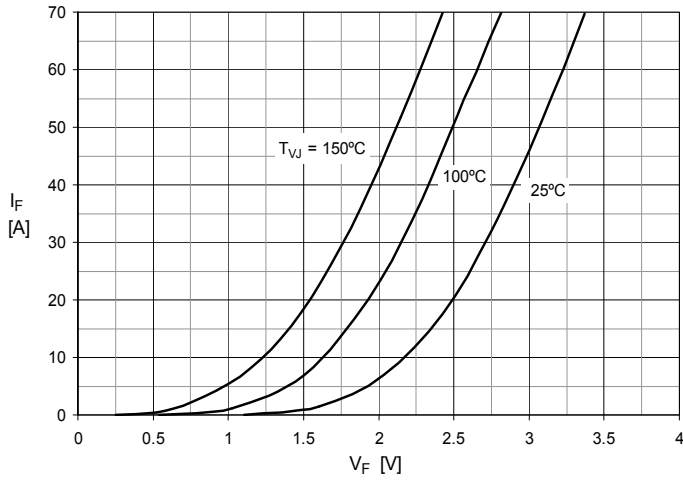
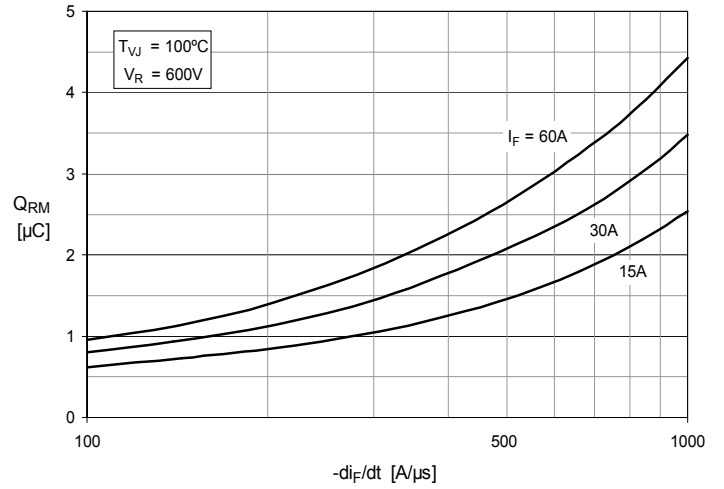
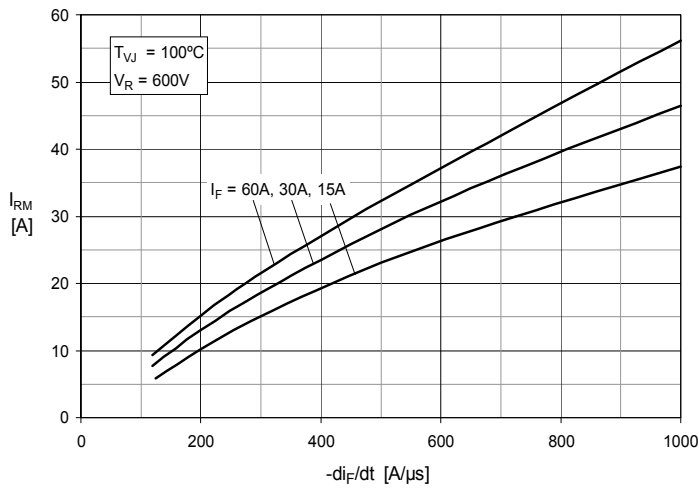
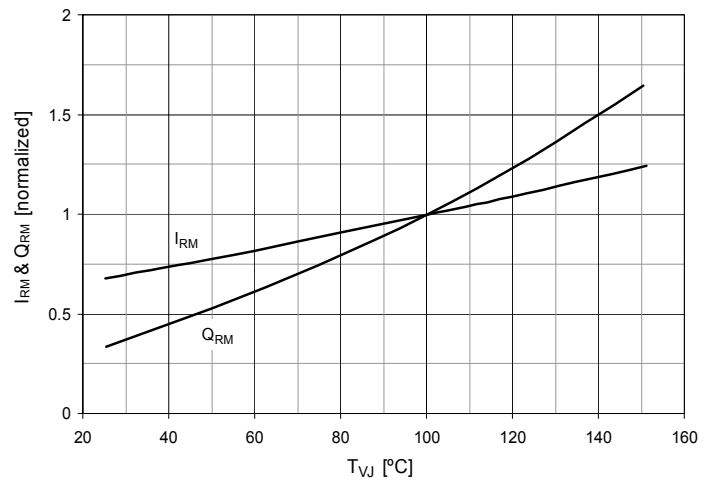
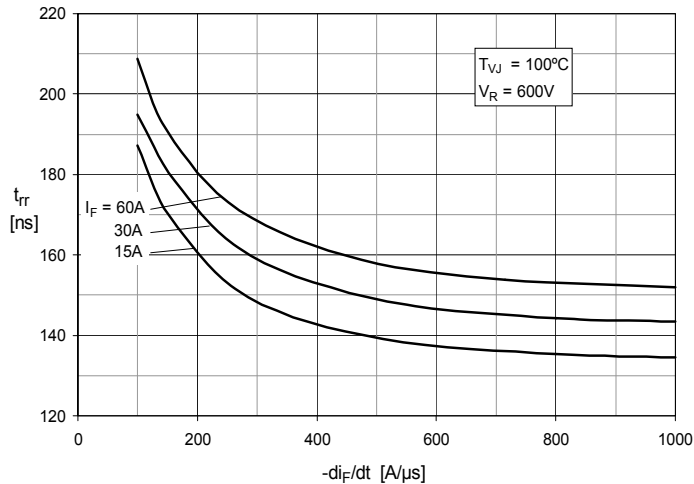
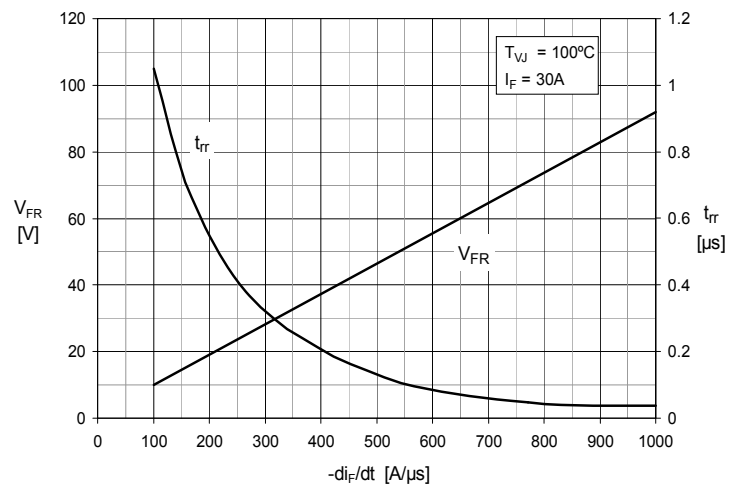


Fig. 22. Forward Current I_F vs V_F

Fig. 23. Reverse Recovery Charge Q_{RM} vs. $-di_F/dt$

Fig. 24. Peak Reverse Current I_{RM} vs. $-di_F/dt$

Fig. 25. Dynamic Parameters Q_{RM} , I_{RM} vs. T_{VJ}

Fig. 26. Recovery Time t_{rr} vs. $-di_F/dt$

Fig. 27. Peak Forward Voltage V_{FR} , t_{rr} vs $-di_F/dt$




Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

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